

SEMICON

Connect to the Center of Microelectronics Design and Manufacturing Innovation

With the world's largest installed fab capacity at more than 4.1 million 200 mm equivalent wafers per month and its high product mix, Japan is well-positioned to meet the rising demands of the ever-changing world of electronics—from innovations in mobile technologies, to the growing world of IoT devices.

Japan: Uniquely Positioned to Support the Internet of Things and More than Moore

With the largest installed 200mm fab capacity, Japan is meeting the needs of a growing market of new devices and technologies that are thriving on low-cost and mature manufacturing processes. As IoT devices continue to drive demand for 200mm manufacturing capacity, Japan provides growing opportunities for upgrading, engineering, and expanding 200 mm technologies and services.

Japan's experience and expertise in microelectronics manufacturing innovation is also serving the demands of the "More than Moore" market, with leadership in MEMS, sensors, and power semiconductors, as well as expanding new markets in areas including automotive and med-tech.

SEMICON[®] Japan puts you in the heart of this exciting market and connects you to buyers and opportunities across the microelectronics ecosystem. Serving as an "Information Hub" for the supply chain, SEMICON Japan connects engineers, executives, buyers, and sellers through a network of exhibits, forums, programs, and engagement events designed to showcase the latest innovations in microelectronics—from silicon to system and everything in between.

SEMICON Japan Highlights:

- One of the largest events for microelectronics in Japan, with more than 700 exhibitors and 35,000 attendees
- Only exposition in Japan covering entire semiconductor supply chain, front-end and back-end
- Co-located with the World of IoT, a "show-within-a-show" dedicated to Internet of Things applications that are driving the next wave of microelectronics innovation

62%

of visitors involved in buying decisions

36%

of visitors represent engineering job functions

48%

of visitors are management level or above

Co-located with

**WORLD OF
IoT**

モノのインターネット

2016 Exhibit Options

Main Exhibit Zones

Raw Space*	Price per 9m ² booth	
	Regular Rate	2015 Exhibition Rate**
SEMI Member	Y400,500	Y346,500
Non-member	Y549,000	Y486,000

World of IoT and Special Pavilions

Raw Space*	Price per 9m ² booth	
	Regular Rate	2015 Exhibition Rate**
SEMI Member	Y400,500	Y346,500
Non-member	Y549,000	Y486,000

	Price per 4m ² booth	
	Regular Rate	2015 Exhibition Rate**
SEMI Member	Y220,000	Y196,000
Non-member	Y240,000	Y224,000

Decorated Space [†]	Price per 2m ² booth	
	Regular Rate	2015 Exhibition Rate**
SEMI Member	Y150,000	Y140,000
Non-member	Y180,000	Y170,000

* Raw space is the rental of floor space only and does not include utilities, services, walls, carpet, furnishings, labor, or material handling.

** Special pricing for 2015 exhibitors

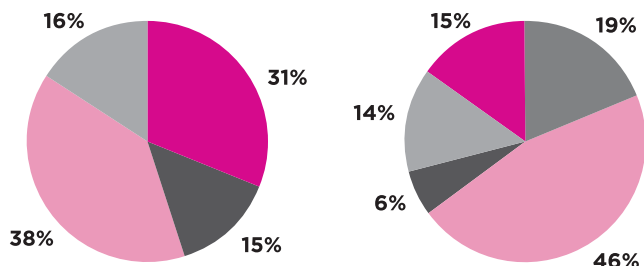
† 2m² decorated package includes hardwall structure, company name fascia, carpet, counter, stool, 1k watt electrical outlet, and lighting.

Contact

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SEMICON® Japan Visitor Profile

SEMICON Japan attracts a highly influential audience from every segment and sector of the global microelectronics industries, including semiconductors, LEDs, OLEDs, MEMS, printed/flexible electronics, and other adjacent markets.



SEMICON Japan 2014 Post-show Data*

Cumulative Daily Attendees**	60,211
Total Verified Visitors	28,223
Total Exhibiting Companies	725
Net Exhibit Area	13,938 sqm.

*2014 Event Data

**Total of daily visitors, exhibitors and program attendees

PURCHASING AUTHORITY

- 16% Final Decision Maker
- 31% Recommend/Evaluate
- 15% Specify
- 38% No Role/Other

JOB LEVELS

- 14% Executive Management
- 15% Senior Management
- 19% Other Management
- 46% Non-management
- 6% Other

Key Visiting Companies and Organizations

SEMICON Japan attracts visitors from every major semiconductor companies—IDMs, foundries, OSATs and fabless those include:

IDMs/FOUNDRIES

Adamant	LG Innotek	Seiko Epson
Akebono Brake Industry	LusemMEMS Core	Seiko Instruments
Alps Electric	Micron	Seiko NPC
Analog Devices	Micron Memory Japan	Seiwa
Asahi Kasei	Mitsubishi Electric	SharpShindengen Electric
Microdevices	Mitsumi Electric	Manufacturing
AU Optronics	Murata Manufacturing	Silicon Sensing
Azbil	NeoPhotonics	Systems
Canon	Semiconductor	SMIC
Citizen Electronics	New Japan Radio	Sony
Cree	Nichia	Spansion
Denso	Nihon Inter	Stanley Electric
Fuji Electric	Electronics	STMicroelectronics
Fuji Xerox	Spansion	Sumitomo Electric
Fujikura	Nissan Motor	Device Innovations
Fujitsu Semiconductor	NTT Electronics	Synaptics
Globalfoundries	Okidata Imaging	Taiwan Semiconductor
Hamamatsu Photonics	Okidata Industry	Taiyo Yuden Mobile
Hitachi Power	Olympus	Technology
Semiconductor	Omnron	Taleson Power
Device	ON Semiconductor	TDK
Hitachi	Origin Electric	Telechips
Honeywell	Ortustech	Texas Instruments
Hokuriku Electric	Panasonic	Torex Semiconductor
Industry	Phenitex	Toshiba
Honda R&D	Semiconductor	TowerJazz Panasonic
IBM	Pioneer Micro	Semiconductor
Infinion Technologies	Technology	Toyoda Gosei
Innolux	PowelQD Laser	Toyota Motor
Intel	Renesas Electronics	Transphorm
Japan Display	Richardson RFPD	Trina Solar
Kaneka	Ricoh Electronic	TriQuint
Konica Minolta	Devices	Semiconductor
Kyocera Corporation	Rohm	TSMC
Kyodo International	Samsung Electronics	Vishay
Lapis Semiconductor	SanDisk Limited	Yamaha
	Sanken Electric	Yokogawa Electric
	Sansha Electric	
	Manufacturing	

FABLESS

ACT LSI	Lsi Technology	Solomon Systech
Aisin	Megachips	Spansion Innovates
Axell	NDK Semiconductor	Steady Design
Imagination Technologies	Revsonic	StepTechnica
LE Tech	Shikino High-Tech	Summit Semiconductor
	Silicon Artist Technology	THine Electronics

OSATs

Amkor Technology	J-Device	Renesas Semiconductor
Aoi Electronics	Katoh Electric	Package & Test Solutions
ARS	Kyec Japan	Shiima Electronics
ASE Group	kyusyudensi	STK Technology
AT Semicon	Mitsui High-tec	STS Semiconductor
Chuo Denshi Kogyo	Mtexp Matsumura	Syswave
Connectec Japn	Naito Densai Kogyo	TDI Product Solution
Creative Electronic	NEPES	TeraProbe
Denken	Oita Device Technology	ZyCube
Hamada Technos		

Areas of Interest

MANUFACTURING

Semiconductor Device Manufacturing (IDM, foundry)	31%
Assembly and Test Services	10%
Fabless Semiconductor Manufacturer/Design Services	10%
Electronic Manufacturing Services (EMS)	9%
Other Manufacturing	8%

MANUFACTURING EQUIPMENT

Wafer Processing/Front-end Manufacturing Equipment	32%
Inspection and Measurement/Metrology Products	27%
Thin Film Manufacturing Equipment	21%
Flat Panel Display Manufacturing Equipment	16%
Test Equipment	16%
Assembly and Packaging Equipment	15%
Secondary Equipment and Services	7%
Other Equipment	8%

MATERIALS

Wafers and Substrates	18%
Process Materials	17%
Chemicals and Solids	13%
Assembly and Packaging Materials	10%
Test Materials	7%
Gases	6%
Other Materials	8%

COMPONENTS/SUB-SYSTEMS/SOFTWARE

Components, Parts and Accessories	12%
Factory Control Automation/Facilities	9%
Software—Manufacturing/Factory Automation	4%
Software—Electronic Design (EDA)/Silicon Intellectual Property (IP)	3%
Sub-systems	2%

SERVICES/SUPPORT PRODUCTS

Business Services or Consulting	3%
Manufacturing Services or Manufacturing Consulting	3%
Support Products (includes consumables)	3%
Other	8%

Partial list and data; see the SEMICON Japan 2014 Post-Show Report online at www.semiconjapan.org for additional data and information.